

### **Discription**

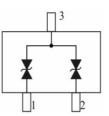
The HESDNC5VB2I-A protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD. It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.



SOT-23

# **Features**

- ★ Low Leakage
- ★ IEC61000-4-2 Level 4 ESD Protection
- ★ We declare that the material of product compliant with RoHS requirements and Halogen Free.
- ★ S- Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.



Circuit Diagram

### **Ordering information**

Product ID	Pack	Qty(PCS)
HESDNC5VB2I-A	SOT-23	3000

## Absolute Ratings (T<sub>amb</sub>=25°C)

Symbol	Parameter	Value	Units
P <sub>PP</sub>	Peak Pulse Power (t <sub>p</sub> = 8/20μs)	100	W
TL	Maximum lead temperature for soldering during 10s	260	°C
T <sub>stg</sub>	Storage Temperature Range	-55 to +150	°C
T <sub>op</sub>	Operating Temperature Range	-55 to +125	°C
Tj	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD) air discharge contact discharge	±30 ±30	KV
	IEC61000-4-4 (EFT)	15	А



#### **ELECTRICAL CHARACTERISTICS**

	V <sub>RWM</sub> (V)	I <sub>R</sub> (μΑ) @ V <sub>RWM</sub>	V <sub>BR</sub> (V) @ I <sub>T</sub> (Note 1)		I <sub>T</sub>	V <sub>C</sub> (V) @ I <sub>PP</sub> = 1 A (Note 2)	V <sub>C</sub> (V) @MAX I <sub>PP</sub> (Note 2)	I <sub>PP</sub> (A) (Note 2)	P <sub>PK</sub> (W) (Note 2)	C (pF)
Device	Max	Max	Min	Max	mA	Max	Max	Max	Max	Тур
HESDNC5VB2I-A	5	1	6	8	1	8	9	11	100	20

Other voltage available upon request.

- 2. Surge current waveform per Figure 1.

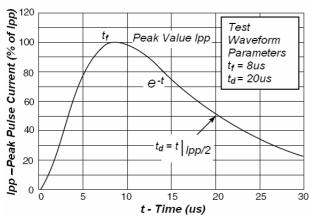


Fig1. Pulse Waveform

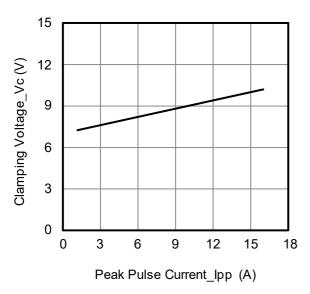


Fig3 .Clamping Voltage vs. Peak Pulse Current

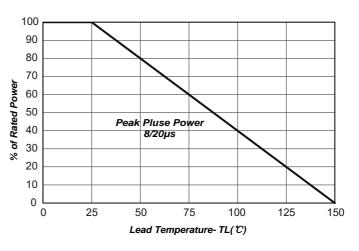


Fig2.Power Derating Curve

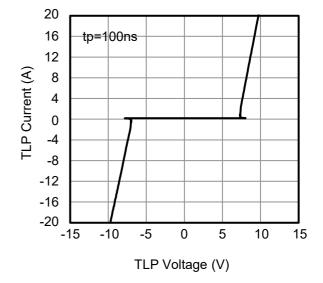
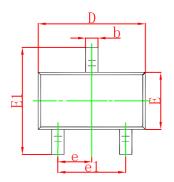
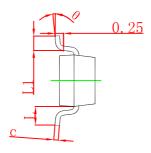
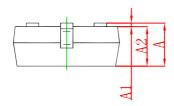


Fig 4. TLP Measurement

# **SOT-23 Package Outline Dimensions**

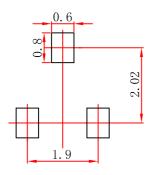






Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

# **SOT-23 Suggested Pad Layout**



#### Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
  3.The pad layout is for reference purposes only.

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